



# Product data sheet

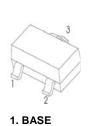
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SOT - 23



2. EMITTER

3. COLLECTOR

#### TRANSISTOR (PNP)

#### FEATURES

- As complementary type, the NPN transistor MMBT3904-MS is Recommended
- Epitaxial planar die construction

MARKING: 2A

#### MAXIMUM RATINGS (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V <sub>CBO</sub>	Collector-Base Voltage	-40	V
V <sub>CEO</sub>	Collector-Emitter Voltage	-40	V
V <sub>EBO</sub>	Emitter-Base Voltage	-5	V
lc	Collector Current -Continuous	-0.2	А
Pc	Collector Dissipation	0.2	W
Rıja	Thermal resistance junction to ambient	625	°C/W
T <sub>J</sub> ,T <sub>stg</sub>	Operation Junction and Storage Temperature Range	-55~+150	°C

#### ELECTRICAL CHARACTERISTICS (Tamb=25℃ unless otherwise specified)

Parameter	Symbol	Test conditions	MIN	MAX	UNIT
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	I <sub>C</sub> =-10μA, I <sub>E</sub> =0	-40		V
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> = -1mA, I <sub>B</sub> =0	-40		V
Emitter-base breakdown voltage	V <sub>(BR)EBO</sub>	I <sub>E</sub> = -10μΑ, I <sub>C</sub> =0	-5		V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = -40 V, I <sub>E</sub> =0		-100	nA
Collector cut-off current	I <sub>CEX</sub>	V <sub>CE</sub> =-30V, V <sub>BE(off)</sub> =-3V		-50	nA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = -5V, I <sub>C</sub> =0		-100	nA
	h <sub>FE1</sub>	$V_{CE}$ =-1V, I <sub>C</sub> = -10mA	100	300	
DC current gain	h <sub>FE2</sub>	V <sub>CE</sub> = -1V, I <sub>C</sub> =-50mA	60		
	h <sub>FE3</sub>	V <sub>CE</sub> = -2V, I <sub>C</sub> =-100mA	30		
Collector-emitter saturation voltage	V <sub>CE(sat)1</sub>	$I_{C}$ =-50mA, $I_{B}$ =-5mA		-0.3	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	I <sub>C</sub> = -50mA, I <sub>B</sub> =-5mA		-0.95	V
Transition frequency	f⊤	$V_{CE}$ =-20V,I <sub>C</sub> =-10mA,f=100MHz	300		MHz
Delay Time	td	V <sub>CC</sub> =-3V,V <sub>BE</sub> =-0.5V		35	nS
Rise Time	tr	I <sub>C</sub> =-10mA, I <sub>B1</sub> =I <sub>B2</sub> =-1mA		35	nS
Storage Time	ts	V <sub>CC</sub> =-3V,I <sub>C</sub> =-10mA		225	nS
Fall Time	tf	I <sub>B1</sub> =I <sub>B2</sub> =-1mA		75	nS

#### CLASSIFICATION OF h<sub>FE(1)</sub>

HFE	100-300		
RANK	L	н	
RANGE	100 - 200	200 - 300	



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-30 -100

-200

β=10

-200

-100

f=1MHz  $I_{e}=0/I_{c}=0$ T\_=25℃

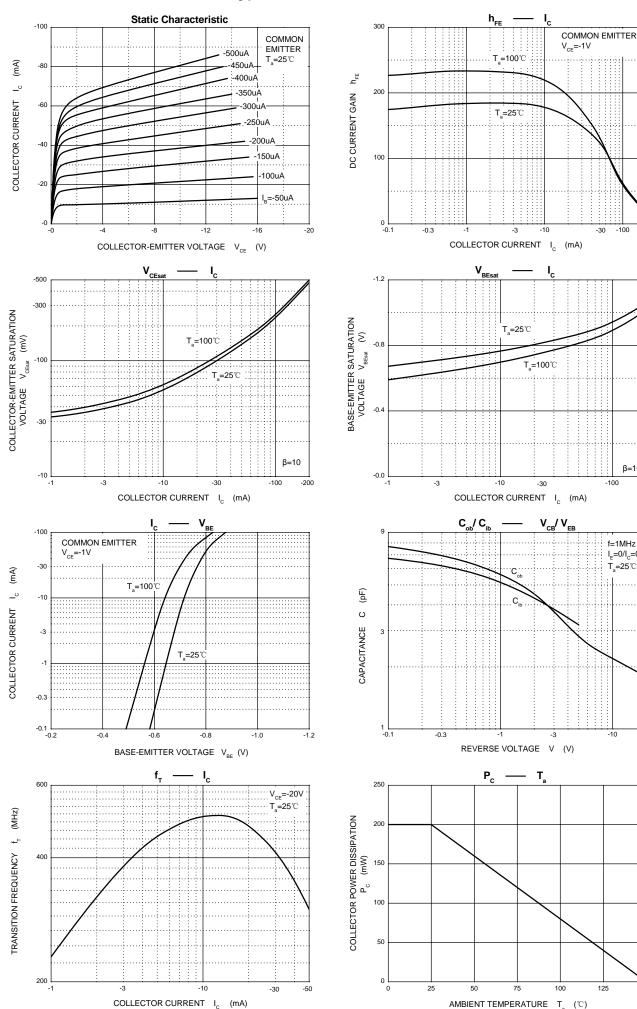
-10

-20

(mA)

Compiance

#### **Typical Characteristics**



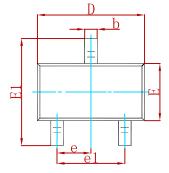
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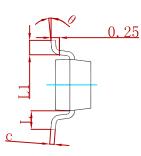
150

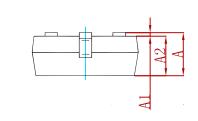
125



## PACKAGE MECHANICAL DATA

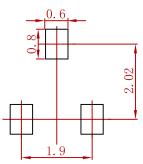






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

## Suggested Pad Layout



Note:

Controlling dimension:in millimeters.
General tolerance:± 0.05mm.
The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
MMBT3906-MS	SOT-23	3000



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